Title (en)

ELECTRICAL OR ELECTRONIC COMPOSITE COMPONENT AND METHOD FOR PRODUCING AN ELECTRICAL OR ELECTRONIC COMPOSITE COMPONENT

Title (de)

ELEKTRISCHES ODER ELEKTRONISCHES VERBUNDBAUTEIL SOWIE VERFAHREN ZUM HERSTELLEN EINES ELEKTRISCHEN ODER ELEKTRONISCHEN VERBUNDBAUTEILS

Title (fr)

COMPOSANT ÉLECTRIQUE OU ÉLECTRONIQUE COMPOSITE ET PROCÉDÉ DE FABRICATION D'UN COMPOSANT ÉLECTRIQUE OU ÉLECTRONIQUE COMPOSITE

Publication

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Application

EP 09764842 A 20091207

Priority

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Abstract (en)

[origin: WO2010072555A1] The invention relates to an electrical or electronic composite component (1), comprising a first joining partner (2) and at least one second joining partner (3). According to the invention, an openly porous sintered molding (6, 7) is held between the first and the second joining partners (2, 3) and is firmly connected to the first and the second joining partners (2, 3).

IPC 8 full level

H01L 23/36 (2006.01); **H01L 23/373** (2006.01)

CPC (source: EP US)

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Citation (search report)

See references of WO 2010072555A1

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- EP 0275433 A1 19880727 - SIEMENS AG [DE]
- JP 3120826 B2 20001225

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